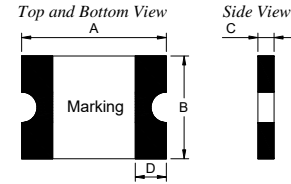


1、 Physical Dimensions(size of 1206)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
KNSMD035/30	3.00	3.40	1.40	1.80	0.75	1.45	0.25	T04



2、 Electrical Characteristics

Part Number	I_H (A)	I_T (A)	V_{max} (V)	I_{max} (A)	T_{trip} (Max time to trip)		Pd_{typ} (W)	R_{min} (Ω)	$R1_{max}$ (Ω)
					Current(A)	Time(S)			
KNSMD035/30	0.35	0.75	30	40	8.00	0.10	0.60	0.300	1.750

I_H : Holding Current: maximum current at which the device will not trip in 25°C still air.

I_T : Tripping Current minimum current at which the device will trip in 25°C still air.

V_{max} : Maximum voltage device can withstand without damage at rated current.

I_{max} : Maximum fault current device can withstand without damage at rated voltage.

T_{trip} : Maximum time to trip(s) at assigned current.

Pd_{typ} : Rated working power.

R_{min} : Minimum resistance of device prior to trip at 25°C.

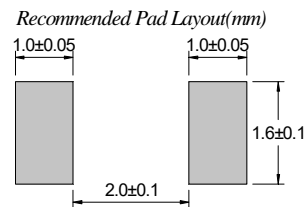
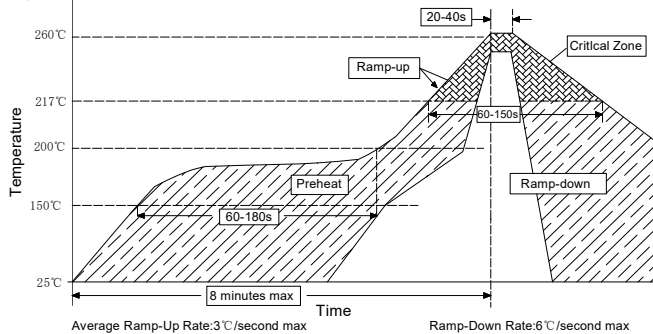
$R1_{max}$: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

3、 Thermal Derating

KNSMD035/30	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	0.51	0.46	0.40	0.35	0.30	0.27	0.24	0.22	0.18
Trip Current(A)	1.09	0.99	0.86	0.75	0.64	0.58	0.51	0.47	0.39

4、 Solder Reflow Recommendations



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5、 Package Information

Packing quantity: 4000PCS/Reel

Note: Reel packaging per EIA-481-1 standard